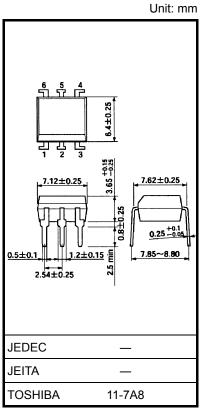
TOSHIBA Photocoupler GaAlAs IRED + Photo IC

TLP512

Digital Logic Ground Isolation
Line Receiver
Microprocessor System Interfaces
Switching Power Supply Feedback Control
Transistor Inverter

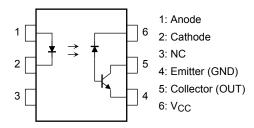
The TLP512 consists of a GaA ℓ As high-output light emitting diode and a high-speed detector that contains a PN photodiode and an amplifier transistor into a single chip.

- Isolation voltage: 2500 Vrms (min)
- Switching speed: t_{pHL} = 0.8 μs , t_{pLH} = 0.8 μs (max) @RL = 1.9 $k\Omega$
- TTL compatible
- UL recognized: UL1577, file No. E67349

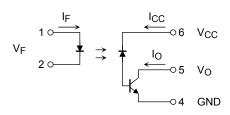


Weight: 0.4 g (typ.)

Pin Configuration (top view)



Schematic



Absolute Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit
	DC forward current	(Note 1)	lF	25	mA
	Pulse forward current	(Note 2)	I _{FP}	50	mA
LED	Peak transient forward current	(Note 3)	I _{FPT}	1	Α
	DC reverse voltage		V_{R}	5	V
	Diode power dissipation	(Note 4)	P_{D}	45	mW
	Output current		IO	8	mA
ō	Peak output current		I _{OP}	16	mA
Detector	Output voltage		Vo	–0.5 to 15	V
ă	Supply voltage		V _{CC}	–0.5 to 15	V
	Output power dissipation	(Note 5)	Po	100	mW
Oper	Operating temperature range			-55 to 100	°C
Storage temperature range			T _{stg}	-55 to 125	°C
Soldering temperature (10 s) (Note 6)			T _{sol}	260	°C
Isola	Isolation voltage (R.H. ≤ 60%, AC 1 min) (Note 7)			2500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Decreases at the rate of 0.8 mA/°C with the ambient temperature of 70°C or higher.
- Note 2: Duty cycle of 50%, pulse width of 1 ms.

 Decreases at the rate of 1.6 mA/°C with the ambient temperature of 70°C or higher.
- Note 3: Pulse width \leq 1 μ s, 300 pps
- Note 4: Decreases at the rate of 0.9 mW/°C with the ambient temperature of 70°C or higher.
- Note 5: Decreases at the rate of 2 mW/°C with the ambient temperature of 70°C or higher.
- Note 6: Soldering is performed 2 mm from the bottom of the package.
- Note 7: Device considered a two-terminal device: pins 1, 2, and 3 shorted together and pins 4, 5 and 6 shorted together.

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Electrical Characteristics (Ta = 25°C)

	Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
LED	Forward voltage	V _F	I _F = 16 mA	_	1.65	1.85	V
	Forward voltage temperature coefficient	ΔV _F /ΔTa	I _F = 16 mA	_	-2	_	mV/°C
	Reverse current	I _R	V _R = 5 V	_	_	10	μА
	Pin-to-pin capacitance	C _T	V _F = 0, f = 1 MHz	_	4.5	_	pF
Detector	High-level output current	I _{OH} (1)	$I_F = 0 \text{ mA}, V_{CC} = V_O = 5.5 \text{ V}$	_	3	500	nA
		I _{OH} (2)	$I_F = 0 \text{ mA}, V_{CC} = V_O = 15 \text{ V}$	_	_	5	
		ІОН	$I_F = 0$ mA, $V_{CC} = V_O = 15$ V Ta = 70°C	_	_	50	μΑ
	High-level supply current	Іссн	I _F = 0 mA, V _{CC} = 15 V	_	0.01	1	μА

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Current transfer ratio	lo/le	$I_F = 16 \text{ mA}, V_{CC} = 4.5 \text{ V}$ $V_O = 0.4 \text{ V}$	20	40	_	- %
Current transfer fatto	I _O /I _F	I _F = 16 mA, V _{CC} = 4.5 V V _O = 0.4 V, Ta = 0 to 70°C	15	_	_	
Low-level output voltage	V _{OL}	I_F = 16 mA, V_{CC} = 4.5 V I_O = 2.4 mA	l		0.4	٧

Isolation Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance input to output	Cs	$V_S = 0$, $f = 1$ MHz (Note 7)	_	8.0	_	pF
Isolation resistance	R _S	R.H. \leq 60%, V _S = 500 V (Note 7)	5 × 10 ¹⁰	10 ¹⁴	_	Ω
		AC 1 min	2500	_	_	Vrmo
Isolation voltage	BV_S	AC 1 s, in oil	_	5000	_	pF
		DC 1 min, in oil	_	5000	_	V _{dc}

Switching Characteristics (Ta = 25°C)

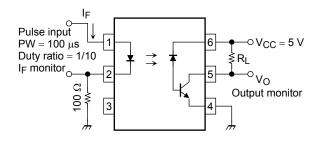
Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Propagation delay time $(H \rightarrow L)$	t _{pHL}	1	$I_F = 0 \rightarrow 16$ mA, $R_L = 1.9$ k Ω	_	_	0.8	μS
Propagation delay time (L \rightarrow H)	t _{pLH}	'	$I_F = 16 \rightarrow 0$ mA, $R_L = 1.9$ kΩ	_	_	0.8	μS
Common mode transient immunity at logic high output (Note 8)	CM _H		I_F = 0 mA, V_{CM} = 200 V_{P-P} R_L = 1.9 $k\Omega$	_	1500	_	V/µs
Common mode transient immunity at logic low output (Note 8)	CML		I_F = 16 mA, V_{CM} = 200 V_{P-P} R_L = 1.9 kΩ	_	-1500		V/μs

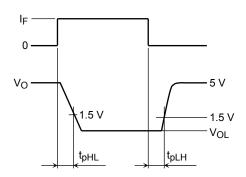
Note 8: Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM}/dt on the leading edge of the common mode pulse, V_{CM} , to assure that the output will remain in a logic high state $(V_{OUT} > 2.0 \text{ V})$.

Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{CM}/dt on the trailing edge of the common mode pulse, V_{CM} , to assure that the output will remain in a logic low state ($V_{OUT} < 0.8 \text{ V}$).

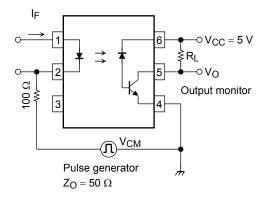
Note 9: Electrostatic discharge immunity (pin to pin): 100 V (max) $(C \le 200 \text{ pF}, R = 0)$

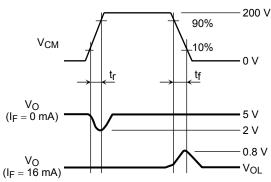
Test Circuit 1: Switching Time Test Circuit



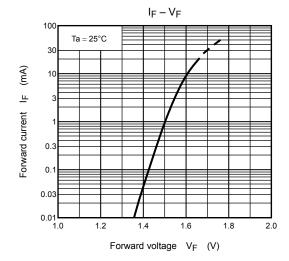


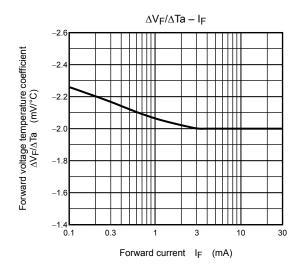
Test Circuit 2: Common Mode Noise Immunity Test Circuit

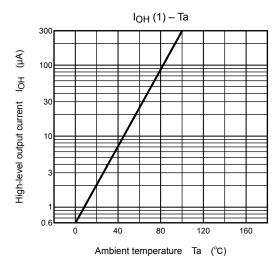


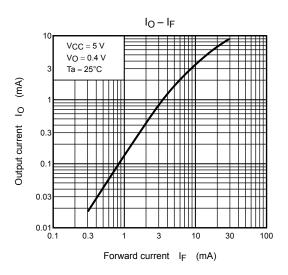


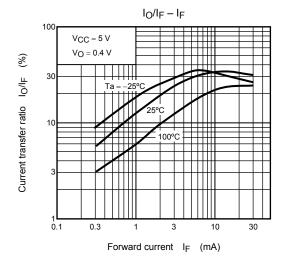
$$CM_{H} = \frac{160 (V)}{t_{r} (\mu s)}, CM_{L} = \frac{160 (V)}{t_{f} (\mu s)}$$

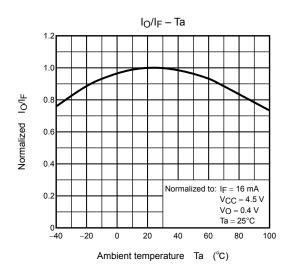






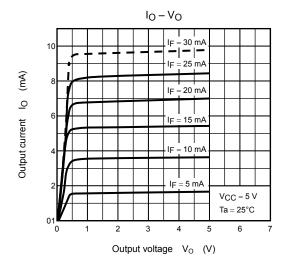


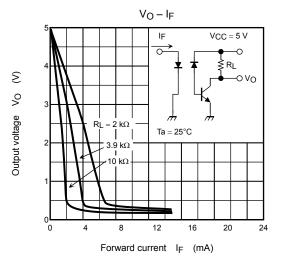


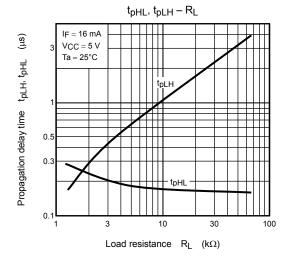


*: The above graphs show typical characteristics.

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^{*:} The above graphs show typical characteristics.

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